

Description

This is 100V 129A N-channel mosfet in a PDFN5060-8L plastic package.

uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

Features

- $V_{DS} = 100\text{ V}$, $I_D = 129\text{ A}$ (Silicon Limited)
 $R_{DS(on)} < 4.2\text{ m}\Omega$ @ $V_{GS} = 10\text{ V}$
 $R_{DS(on)} < 6\text{ m}\Omega$ @ $V_{GS} = 4.5\text{ V}$
- Green device available
- 100% EAS guaranteed
- Optimized for high speed smooth switching

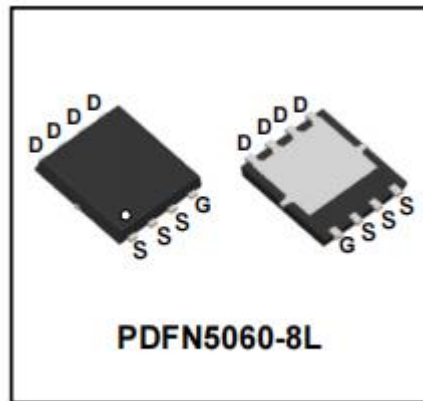
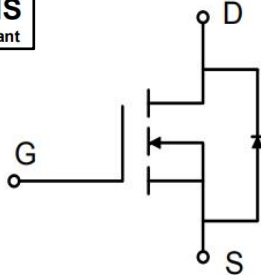
Applications

- Power management switches
- DC/DC converter

V_{DSS}	$R_{DS(on)}$	I_D
100 V	4.2 m Ω	129 A

Equivalent Circuit & Pinning

RoHS
compliant



Absolute Maximum Ratings(Ta=25°C)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	100	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current ¹ (Silicon Limited)	$T_C=25^{\circ}\text{C}$	I_D	129	A
	$T_C=100^{\circ}\text{C}$		80	
	$T_C=25^{\circ}\text{C}$		60	
Continuous Drain Current ¹ (Package Limited)				
Pulsed Drain Current ²		I_{DM}	402	A
Single Pulse Avalanche Energy ³		E_{AS}	101.2	mJ
Avalanche Current		I_{AS}	45	A
Total Power Dissipation ⁴	$T_C=25^{\circ}\text{C}$	P_D	127.5	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ¹	$R_{\theta JA}$	49	°C/W
Thermal Resistance from Junction-to-Case ¹	$R_{\theta JC}$	0.98	°C/W

Electrical Characteristics(Ta=25°C)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100	-	-	V
Gate-body Leakage Current		I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V	-	-	1	μA
	T _J =100°C			-	-	100	
Gate-Threshold Voltage		V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.4	1.8	2.4	V
Drain-Source On-Resistance ²		R _{DS(on)}	V _{GS} = 10V, I _D = 20A	-	3.5	4.2	mΩ
			V _{GS} = 4.5V, I _D = 20A	-	4.8	6	
Forward Transconductance ²		g _{fs}	V _{DS} = 5V, I _D = 20A	-	81	-	S
Dynamic Characteristics							
Input Capacitance		C _{iss}	V _{DS} = 50V, V _{GS} =0V, f =1MHz	-	3875	-	pF
Output Capacitance		C _{oss}		-	920	-	
Reverse Transfer Capacitance		C _{rss}		-	41	-	
Switching Characteristics							
Gate Resistance		R _g	V _{DS} = 0V, V _{GS} =0V, f =1MHz	-	1.2	-	Ω
Total Gate Charge		Q _g	V _{GS} = 4.5V, V _{DD} = 50V, I _D = 20A	-	52	-	nC
Total Gate Charge		Q _g	V _{GS} = 10V, V _{DS} = 50V, I _D = 20A	-	91	-	
Gate-Source Charge		Q _{gs}		-	7.9	-	
Gate-Drain Charge		Q _{gd}		-	31.5	-	
Turn-On Delay Time		t _{d(on)}	V _{GS} =10V, V _{DS} = 50V, R _G = 10Ω, I _D = 20A	-	15.3	-	nS
Rise Time		t _r		-	17.8	-	
Turn-Off Delay Time		t _{d(off)}		-	52.4	-	
Fall Time		t _f		-	23.6	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage ²		V _{SD}	I _S = 20A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current ^{1,5}		I _S	V _G =V _D =0V , Force Current	-	-	129	A
Reverse Recovery Time		t _{rr}	V _R =50V, I _F =20A, dI _F /dt=500A/μs	-	44	-	ns
Reverse Recovery Charge		Q _{rr}		-	212	-	nC

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=45A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Electrical Characteristic Curve

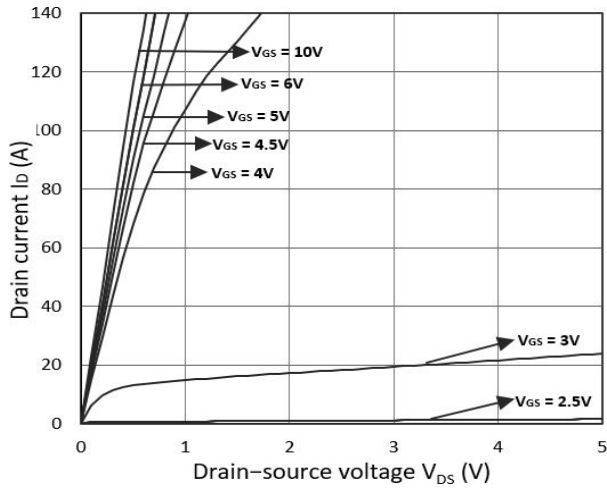


Figure 1. Output Characteristics

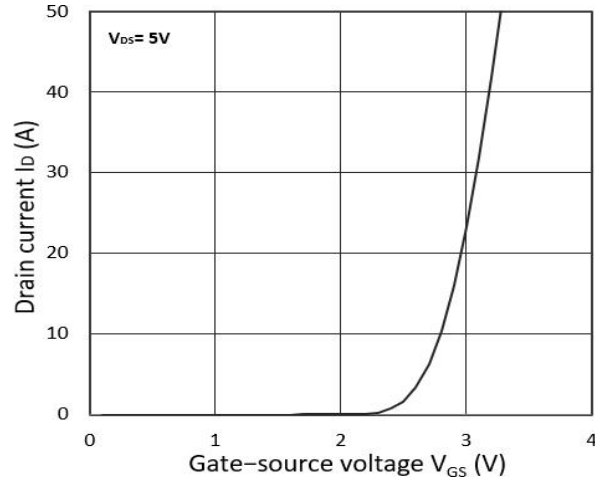


Figure 2. Transfer Characteristics

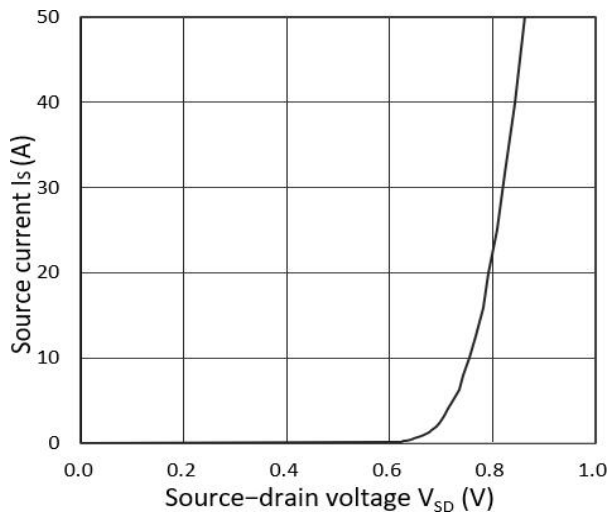


Figure 3. Forward Characteristics of Reverse

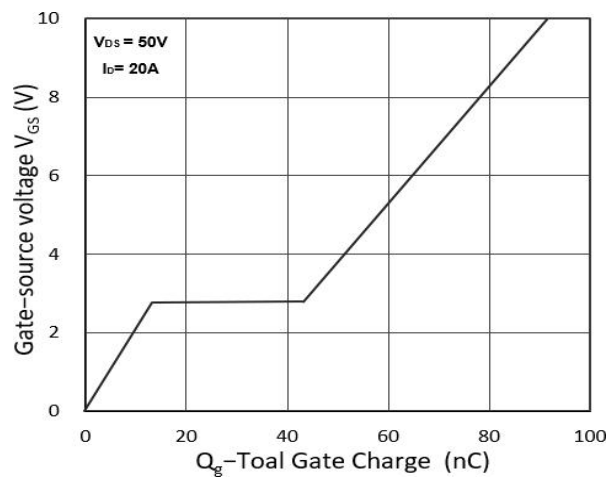


Figure 4. Gate Charge Characteristics

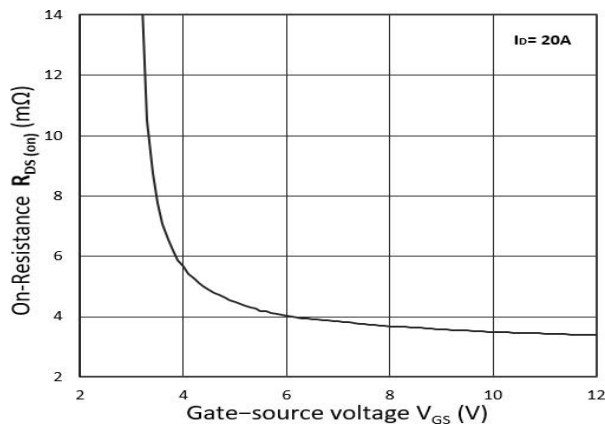


Figure 5. $R_{DS(on)}$ vs. V_{GS}

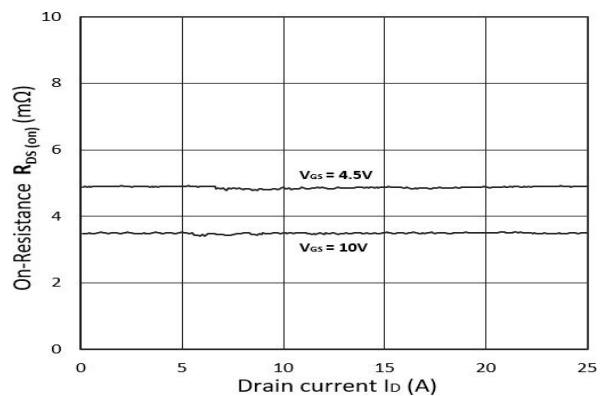


Figure 6. $R_{DS(on)}$ vs. I_D

Electrical Characteristic Curve

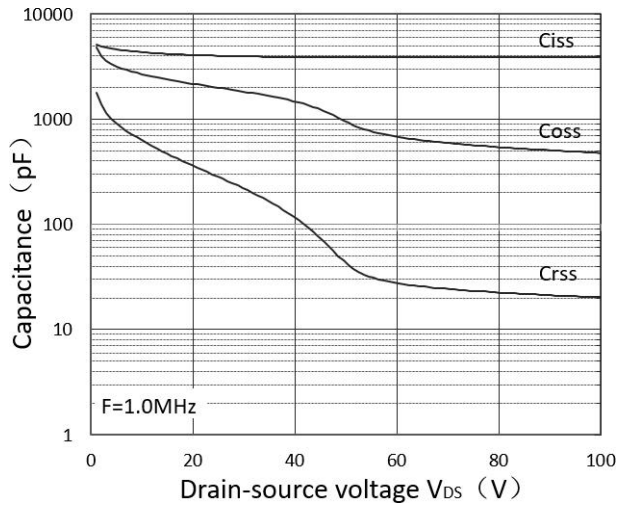


Figure 7. Capacitance Characteristics

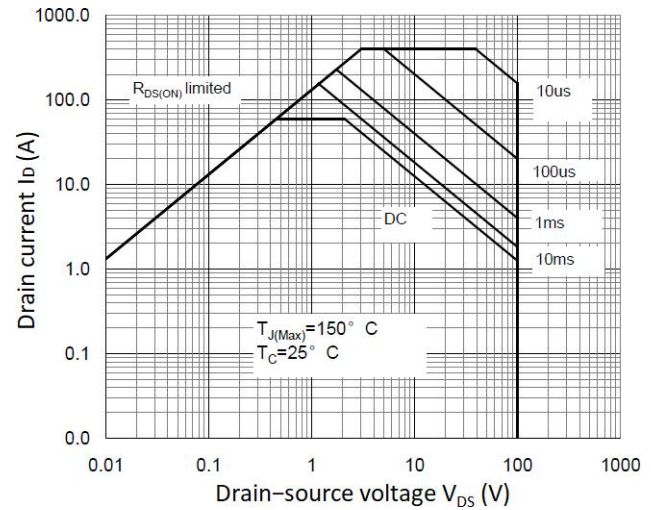


Figure 8. Safe Operating Area

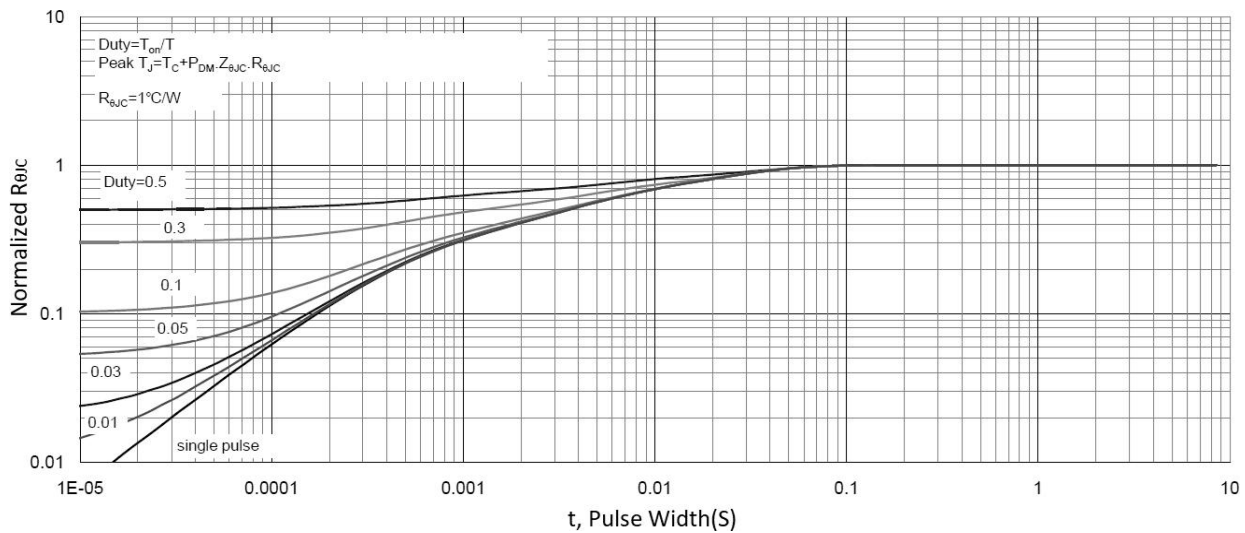


Figure 9. Normalized Maximum Transient Thermal Impedance

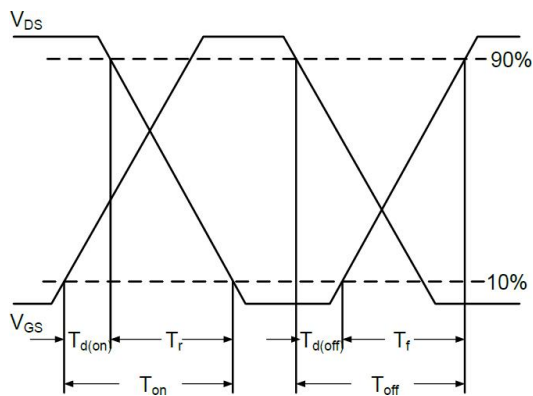


Figure 10. Switching Time Waveform

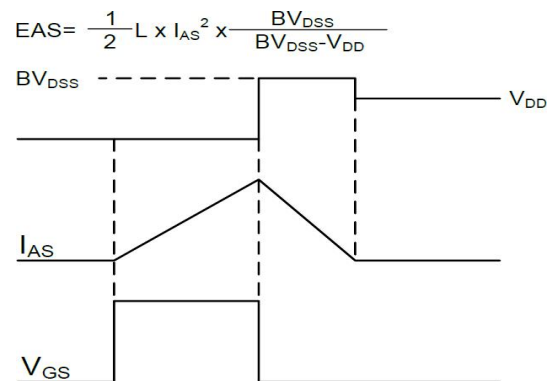
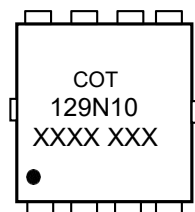


Figure 11. Unclamped Inductive Switching Waveform

Marking Instructions



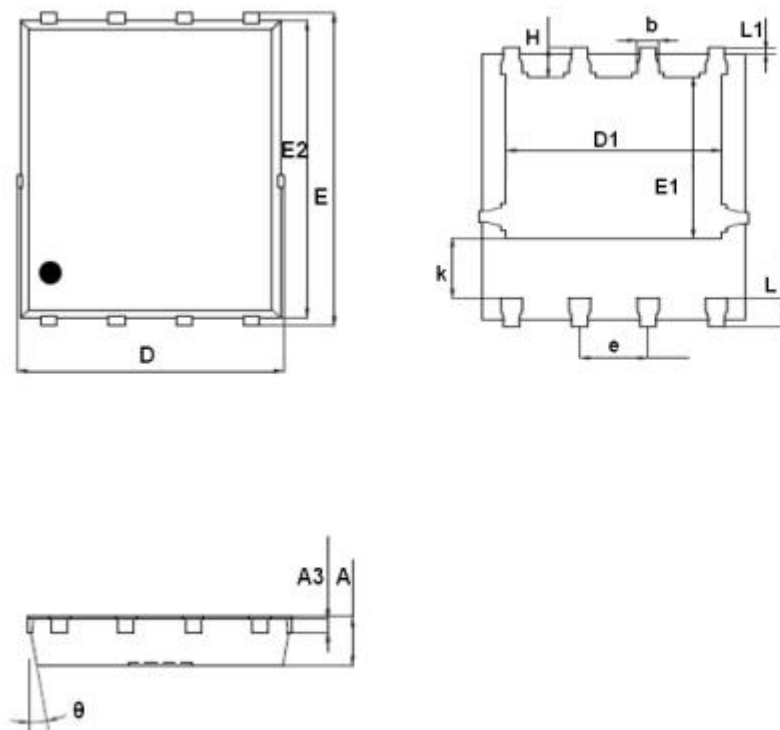
129N10 = Device code
XXXX XXX= Date code

Ordering Information

Part	Package	Marking	Packing method
CT129N10ZC	PDFN5060-8L	129N10	Tape and Reel

Mechanical Dimensions for PDFN5060-8L

COMMON DIMENSIONS



SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.65	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.61
θ	0°	12°